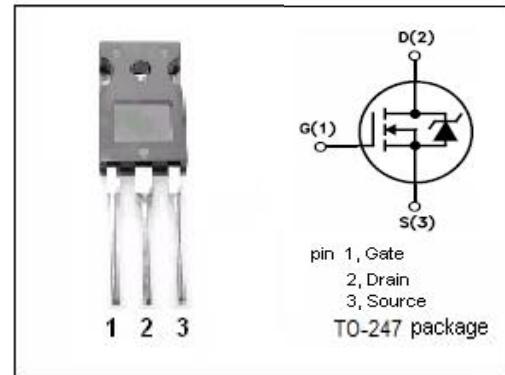


## Isc N-Channel MOSFET Transistor

## STW20NM60FD

### • FEATURES

- Low input capacitance and gate charge
- Low gate input resistance
- 100% avalanche tested
- Tight process control and high manufacturing yields
- Minimum Lot-to-Lot variations for robust device performance and reliable operation



### • APPLICATIONS

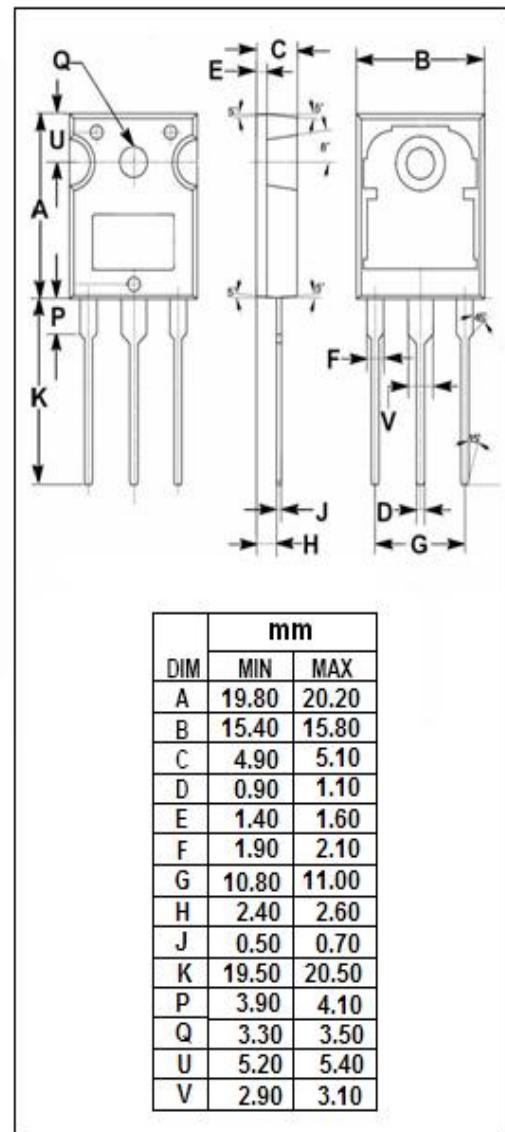
- Switching application

### • ABSOLUTE MAXIMUM RATINGS( $T_a=25^\circ\text{C}$ )

SYMBOL	PARAMETER	VALUE	UNIT
$V_{DSS}$	Drain-Source Voltage	600	V
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current-Continuous@ $T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	20 12.6	A
$I_{DM}$	Drain Current-Single Pulsed	80	A
$P_D$	Total Dissipation	214	W
$T_{ch}$	Max. Operating Junction Temperature	-65~150	°C
$T_{stg}$	Storage Temperature	-65~150	°C

### • THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	0.59	°C/W
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	30	°C/W



**Isc N-Channel MOSFET Transistor****STW20NM60FD****ELECTRICAL CHARACTERISTICS** $T_c=25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}; \text{I}_D= 0.25\text{mA}$	600			V
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\pm 30\text{V}; \text{I}_D=0.25\text{mA}$	3		5	V
$\text{R}_{\text{DS(on)}}$	Drain-Source On-Resistance	$\text{V}_{\text{GS}}= 10\text{V}; \text{I}_D=10\text{A}$		260	290	$\text{m}\Omega$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}= \pm 30\text{V}; \text{V}_{\text{DS}}= 0\text{V}$			$\pm 0.1$	$\mu\text{A}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}= 600\text{V}; \text{V}_{\text{GS}}= 0\text{V}; \text{T}_J=25^\circ\text{C}$ $\text{T}_J=125^\circ\text{C}$			1 10	$\mu\text{A}$
$\text{V}_{\text{SDF}}$	Diode forward voltage	$\text{I}_{\text{SD}}=20\text{A}, \text{V}_{\text{GS}} = 0 \text{ V}$			1.5	V